

## ALPHA<sup>®</sup> CVP-390

No-Clean, Lead-Free Solder Paste Zero-Halogen, Low Voids, Fine Feature, Excellent Pin Test Performance, SAC305, SAC405, & Low Ag Capable

### DESCRIPTION

**ALPHA CVP-390** is a lead-free, zero-halogen no-clean solder paste designed for applications where residue with excellent pin testing property and ability to pass JIS Copper Corrosion test are required.

This product is also designed to enable consistent fine pitch printing capability, down to 180 µm circle printed with 100 µm thickness stencil. Its excellent print volume deposit repeatability also provides value by reducing defects associated with print process variability. Additionally, **ALPHA CVP-390** achieves IPC-7095 Class 3 voiding performance.

READ ENTIRE TECHNICAL DATA SHEET BEFORE USING THIS PRODUCT

### FEATURES & BENEFITS

- **Long Stencil Life:** consistent performance for at least 8 hours of continuous printing without addition of new paste
- **Long, High Tack Force Life:** Ensures high pick-and-place yields, good self-alignment
- **Wide Reflow Profile Window:** Allows best quality solderability of complicated, high density PWB assemblies in both air and nitrogen reflow, using ramp and soak profiles, as high as 175 to 185 °C
- **Reduced Random Solder Ball Levels:** Minimizes rework and increases first time yield
- **Excellent Coalescence and Wetting Performance:** Coalesced 180µm circle deposit, even at high soak profile environment
- **Excellent Solder Joint and Flux Residue Cosmetics:** After reflow soldering, even using long/high thermal soaking, without charring or burning
- **Excellent Voiding Performance:** Meets IPC-7095 Class 3 requirement
- **Halogen Content:** Zero-halogen, no halogen intentionally added
- **Residue:** Excellent Pin Testing property and Pass JIS Copper Corrosion Test
- **Safe and Environmentally Friendly:** Materials comply with RoHS and Halogen-free requirements (see table below), as well as TOSCA & EINECS

**PRODUCT INFORMATION**

<u>Alloys:</u>	SAC105, SAC305, SAC405, SACX Plus 0307 SMT, SACX Plus 0807 SMT, Innolot. For other alloys, contact your local Alpha Sales Office.
<u>Powder Size:</u>	Type 3, Type 4, Type 4.5, Type 5, Type 6, & Type 7
<u>Packaging Sizes:</u>	500 gram jars, 10 cc & 30 cc syringe, 6 in & 12 in cartridges
<u>Flux Gel:</u>	Flux gel is available in 10 and 30 cc syringes for rework applications
<u>Lead Free:</u>	Complies with RoHS Directive EU/2015/863

**APPLICATION GUIDELINES**

Formulated for both standard and fine pitch stencil printing, at print speeds of between 25 mm/sec (1 in/sec) and 150 mm/sec (6 in/sec), with stencil thickness of 0.100 mm (0.004 in) to 0.150 mm (0.006 in), particularly when used in conjunction with ALPHA Stencils. Blade pressures should be 0.21 to 0.36 kg/cm of blade (1.25 to 1.5 lbs/inch), depending upon the print speed. The higher the print speed employed, the higher the blade pressure that is required. The reflow process window will give high soldering yield with good cosmetics and minimized rework.

**HALOGEN STATUS**

**ALPHA CVP-390** is a zero-halogen product and passes the standards listed in the table below:

Halogen Standards			
Standard	Requirement	Test Method	Status
<b>JEITA ET-7304</b> Definition of Halogen-Free Soldering Materials	< 1000 ppm Br, Cl, F in solder material solids	<b>TM EN 14582</b>	Pass
<b>IEC 612249-2-21</b>	Post Soldering Residues contain < 900 ppm each or total of < 1500 ppm Br or Cl from flame retardant source		Pass
<b>JEDEC</b> A Guideline for Defining "Low Halogen" Electronics	Post soldering residues contain < 1000 ppm Br or Cl from flame retardant source		Pass
<b>Zero-Halogen:</b> No halogenated compounds have been intentionally added to this product			

**TECHNICAL DATA**

Category	Results	Procedures/Remarks
<b>Chemical Properties</b>		
Activity Level	ROL0	IPC J-STD-004B
Halide Content	Halide-free (by IC)	IPC J-STD-004B
Fluoride Spot Test	<b>Pass</b>	JIS Z 3197:1999 8.1.4.2.4
Halogen Test	<b>Pass</b> , Zero-halogen - No halogen intentionally added	EN14582, by oxygen bomb combustion, Non-detectable (ND) at < 50 ppm
Ag Chromate Test	<b>Pass</b>	IPC J-STD-004B
	<b>Pass</b>	JIS Z 3197:1999 8.1.4.2.3
Copper Mirror Test	<b>Pass</b>	IPC J-STD-004B
	<b>Pass</b>	JIS Z 3197:1999 8.4.2
Copper Corrosion Test	<b>Pass</b> (No evidence of Corrosion)	IPC J-STD-004B
	<b>Pass</b> (No evidence of Corrosion)	JIS Z 3197:1999 8.4.1
<b>Electrical Properties</b>		
Water Extract Resistivity	13,400 ohm-cm	JIS Z 3197:1999 8.1.1
SIR (7 days, 40 °C/90% RH, 12 V bias)	<b>Pass</b>	IPC J-STD-004B TM-650 2.6.3.7 (Pass $\geq 1 \times 10^8$ ohm)
Electromigration (Bellcore 500 hrs @ 65 °C/85% RH 10V)	<b>Pass</b>	Bellcore GR-78-CORE (Pass=final > initial/10)
JIS Electromigration (1000 hours @ 85 °C/85% RH 48V)	<b>Pass</b>	JIS Z 3197:1999 8.5.4
<b>Physical Properties</b>		
Color	Clear, Colorless Flux Residue	
Tack Force vs. Humidity	<b>Pass</b> , > 100 gf over 24 hours at 25%, 50% and 75 % Relative Humidity	JIS Z-3284-1994, Annex 9
	<b>Pass</b> , Change of <1 g/mm <sup>2</sup> over 24 hours at 25% and 75 % Relative Humidity	IPC J-STD-005 TM-650 2.4.44

Category	Results	Procedures/Remarks
Tack Force at 32 °C/35% RH, measured after 0, 1, 2, 3 & 4 hours print duration	> 100 gf	JIS Z-3284-1994, Annex 9
Viscosity Stability at 25 °C for 20 days	Pass	Malcom Spiral Viscometer
Continuous Viscosity Measurement at 25 °C for 24 hours	Pass	Malcom Spiral Viscometer
Coalescence Test	Able to reflow at < 200 µm Cu pad circle size	Internal
Solder Ball	Preferred	IPC J-STD-005 TM-650 2.4.43
Wetting Time	Pass 0.34 second	Rhesca Test, Test Time T2, 3 seconds
Spread	80%	JIS Z 3197:1999 8.3.1.1
Stencil Life	>8 hours	@ 50% RH 23°C (74 °C)
Cold Slump	No bridge for 0.2 mm space	JIS Z 3284:1994 Annex 7
	Pass	IPC J-STD-005 TM-650 2.4.35
Hot Slump	No bridge for 0.4 mm space	JIS Z 3284:1994 Annex 8
	Pass	IPC J-STD-005 TM-650 2.4.35
Dryness Test (Talc)	Pass	JIS Z 3197:1999 8.5.1

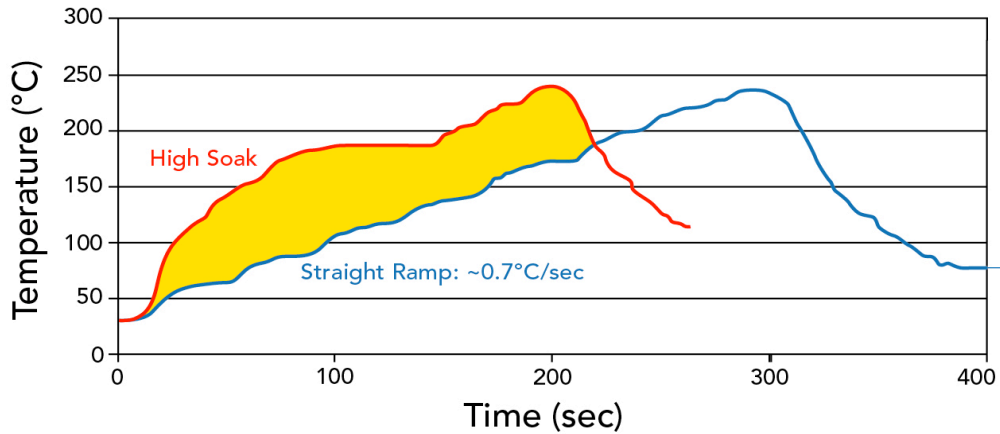
**PROCESSING GUIDELINES\*<sup>1</sup>**

Storage & Handling	Printing	Reflow (See Fig. 1)	Cleaning
<p>1. Refrigerate to guarantee stability @ 0 to 10 °C (32 to 50 °F). When stored under these conditions, the shelf life of ALPHA CVP-390 is 6 months. Refrigeration is recommended for optimal performance.</p> <p>2. Paste can be stored for maximum 2 weeks at room temperature up to 25 °C (77 °F) prior to use.</p> <p>3. Product supplied in cartridge format can be stored vertically (tip down) or horizontally. Rotation of cartridge 180° weekly is recommended for horizontal storage conditions.</p> <p>4. When refrigerated, warm up paste container to room temperature for up to 4 hours. Paste must be 19 °C (66 °F) before processing. Verify paste temperature with a thermometer to ensure paste is at 19 °C (66 °F) or greater before set up of printer.</p> <p>5. Paste can be manually stirred before use. A rotating/Centrifugal force mixing operation is not required. If a rotating/centrifugal force mixing is used, 30 to 60 seconds at 300 RPM is adequate.</p> <p>6. Do not remove worked paste from stencil and mix with unused paste in jar. This will alter the rheology of unused paste.</p>	<p><b>Stencil:</b> Recommend ALPHA CUT, ALPHA NICKEL-CUT, ALPHA TETRABOND, or ALPHA FORM stencils @ 0.100 to 0.150 mm (4 to 6 mil) thick for 0.4 to 0.5 mm (0.016 or 0.020 in) pitch. Stencil design is subject to many process variables. Contact your local Alpha stencil site for advice.</p> <p><b>Squeegee:</b> Metal (recommended)</p> <p><b>Pressure:</b> 0.21 to 0.36 kg/cm of blade (1.25 to 2.0 lbs/inch)</p> <p><b>Speed:</b> 25 to 150 mm per second (1 to 6 inches per second).</p> <p><b>Paste Roll:</b> 1.5 to 2.0 cm diameter and make additions when roll reaches 1 cm (0.4 in) diameter (minimum). Max roll size will depend upon blade.</p> <p><b>Stencil Release Speed:</b> 1 to 5 mm/sec.</p> <p><b>Lift Height:</b> 8 to 14 mm (0.31 to 0.55 in)</p>	<p><b>Atmosphere:</b> Clean-dry air or nitrogen atmosphere.</p> <p><b>Profile (SAC Alloys):</b> <u>Straight Ramp:</u> 0.7 °C/sec &amp; 1.3 °C/sec ramp profiles, 45 to 90 TAL.</p> <p><b>Soak:</b> 155 to 175 °C, 60 to 100 sec soak profiles have been determined to give optimal results. If required, good results are also achievable with high soak temperature profiles of 170 to 185 °C for 60 sec. Typical peak temperature is 235 to 245 °C.</p> <p><b>Note 1:</b> Keeping the peak temperature below 241 °C may reduce the number and size of BGA and QFN voids.</p> <p><b>Note 2:</b> Refer to component and board supplier data for thermal properties at elevated temperatures. Lower peak temperatures require longer TAL for improved joint cosmetics.</p>	<p>ALPHA CVP-390 residue is designed to remain on the board after reflow. If reflowed residue cleaning is required, Vigon A201 (in line cleaning), Vigon A 250 (Batch Cleaning) or Vigon US (Ultrasonic Cleaning) are recommended. Vigon is a registered trademark of Zestron.</p> <p>Misprints and stencil cleaning may be done with IPA, ALPHA SM-110E, ALPHA SM-440, and Bioact SC-10E cleaners. Bioact is a registered trademark of Petroferm.</p>

\* These are starting recommendations and all process settings should be reviewed independently

REFLOW PROFILES

Fig 1: ALPHA CVP-390 SAC305 Typical Reflow Profile



Parameter	Guideline	Additional Information
Atmosphere	Air or N2	
SAC305	217 to 221 °C Melting Range	
SACX Plus 0807 SMT	217 to 225 °C Melting Range	
SACX Plus 0307 SMT	217 to 227 °C Melting Range	
Innolot Alloy	206 to 218 °C Melting Range	
Setting Zone*	Optimal Dwell Period	Extended window
40 to 221 °C	2:30 to 4:30 min	< 5:00 min
170 to 221 °C	0:30 to 2:00 min	< 2:30 min
120 to 221 °C	1:25 to 3:00 min	< 3:30 min
TAL (>221 °C)	45 to 90 sec	Not Recommended
Peak Temperature	235 to 245 °C	Compatible with most common surface finishes. (ENTEK HT, ENTEK OM, Alpha Star, ENIG, SACX HASL). Coldest point on the PCB can be as low as 230 °C. Paste can withstand 250 °C during reflow.
Joint Cool Down Rate	1 to 6 °C/sec	Recommended to prevent surface cracking issues.

Above recommendations are for SAC305.

For alternative alloys, please follow the liquidus temperature of the respective alloy

**SAFETY & WARNING**

It is recommended that the company/operator read and review the Safety Data Sheets for the appropriate health and safety warnings before use. **Safety Data Sheets are available at [macdermidAlpha.com/assembly-solutions/knowledge-base](http://macdermidAlpha.com/assembly-solutions/knowledge-base)**

**CONTACT INFORMATION**

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Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE. Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588

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